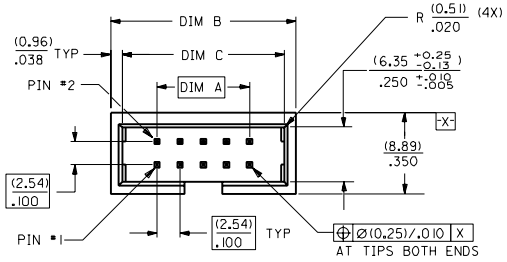
PART NUMBERS	CKT SIZE	DIM A	DIM B $^{+0.20}_{-0}$	DIM C	DIM D
87256-3491	34	(40.64)/1.600	(50.18)/1.975	(48.26)/1.900	(45.72)/1.800

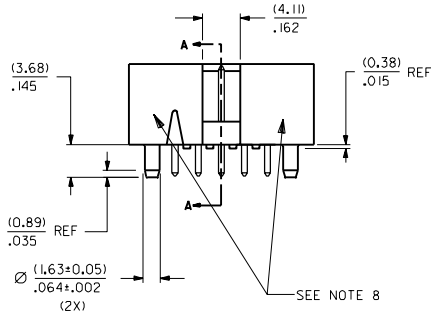
PART NUMBER LEGEND

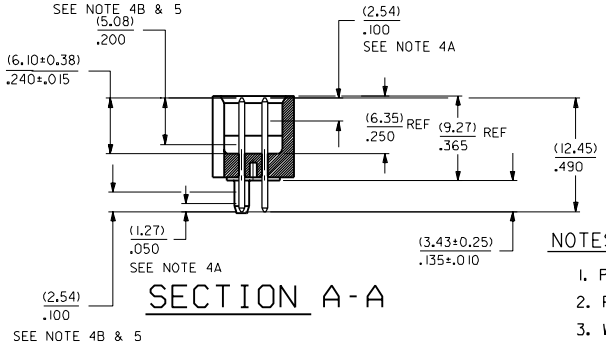
87256 - * * 9 1

CKT SIZE

ASSEMBLY OPTION
91 - BEGIGE





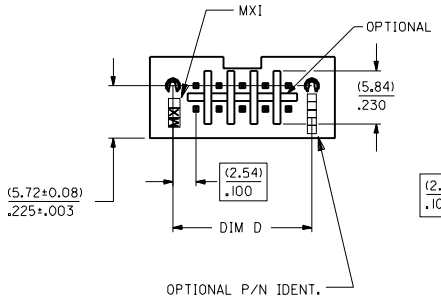


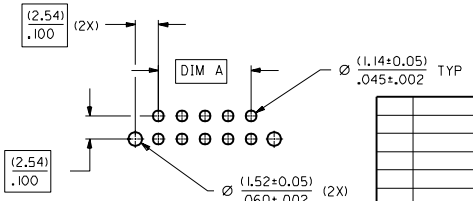
SECTION A-A

NOTES :

1. PIN PUSHOUT FORCE (0.9072 KG)/2 LBS MIN.
2. PRODUCT SPECIFICATION #70246 APPLIES.
3. WAFER TO BE FLAT WITHIN (0.03MM/CM)/.003IN/IN.
4. DIMENSIONS FOR PLATING LOCATIONS : A - MEASURE POINT FOR THICKNESS.
   B - MINIMUM COVERAGE.
5. GOLD END OF PIN UNLESS OVERALL PLATED.
6. FINISH : (PER ES-88)
   0.13um/5u" MIN GOLD FLASH OVER 1.02um/40u" MIN.PD/NI IN SELECTED AREA AND 2.5um/100u" MIN.TIN/LEAD IN SELECTED AREA OVER 1.27um/50u" MIN NICKEL OVERALL
7. FOR ILLUSTRATION PURPOSE A 10 CKT IS SHOWN.
8. OPTIONAL LOCATION FOR WEEK/YEAR STAMP IF REQUIRED BY CUSTOMER

(MM)
INCH





RECOMMENDED PCB PATTERN

LTR	REVISION RECORD	ECN	DR / CHK	DATE
A	REVISE PER ECN# S2486	S2486	JACK SK	920429

REVISE ONLY ON CAD SYSTEM

MATERIAL :
WAFER : HIGH TEMP. THERMOPLASTICS
PINS : (0.64)/.025 SQ CU ALLOY

FINISH :

DRAWN BY KHO O L 900803
CHK'D BY MAX LAI 901128
APPR'D BY ROY WONG
SCALE 2:1

MOLEX
F.E.M.L South
SHEET 1 OF 1

GENERAL TOLERANCES ± 0.20/.008
REV A

DWG. NO.: SD 87256-**91

TITLE : C-GRID, SHROUDED WAFER SLOTTED, WITH IN-LINE POLARIZATION PEGS

DWG. NO. SD 87256-**91
CAD FILE S8725691.DGN
DO NOT SCALE DRAWING

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX (FEML) AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION